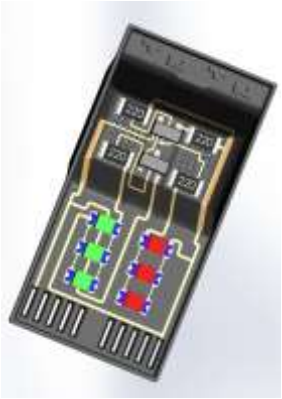
Electronics – Molded Interconnected Device

Application	Molded connector
Material	Special LCP – Vectra
Mold	2 cavity
Part Weight	0.51 gram
Note	0.007” micro features
Machine	LP20EH3 P12S14

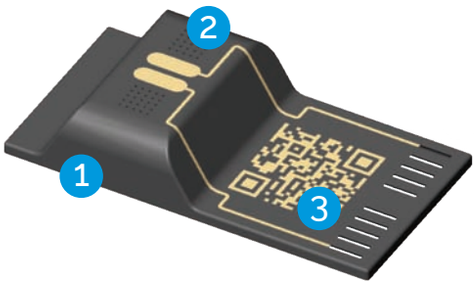
Celanese, Mold Craft, LPKF and Sodick have teamed together demonstrating a complex MID (molded interconnected device) molding development.

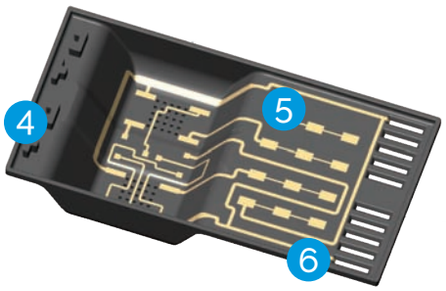


MINIATURIZATION
is a BIG OPPORTUNITY

Miniaturization is a top priority of all advanced sensor and electronics technology manufacturers. Whether it is an automotive application, a connectivity device, or an appliance, consumers are looking for smaller, lightweight products with advanced features. With this objective in mind, Celanese, Mold Craft, Sodick, and LPKF have teamed together demonstrating the innovative value propositions that exist for device manufacturers when choosing these industry-leading experts as partners for their sensor design and manufacturing needs.

MOLDED INTERCONNECT DEVICE (MID)





1. **Micro Thin Walled Part:** A Precision mold coupled to the precise shot control of a Sodick molding machine running low viscosity Vectra® LCP yields high quality parts.
2. **Molded Fine Pitch Holes:** Fifty .007" X.007" holes molded directly into the part with Mold Craft's ability to design for manufacturing.
3. **Custom QR Code:** Created directly on the part through LDS (Laser Direct Structuring).
4. **Micro Features:** The incredible precision of Mold Craft's machining allows mold insert and final part radii to be as small as .002"
5. **High Melt Temperature:** Electrical components can be soldered directly onto the part using LDS and Celanese's High Performance Vectra® LCP.
6. **LDS Process:** Complex, complete circuits can be created on both sides of the part by plating angled through holes from front to back.

Learn more about this process by scanning the QR code.